

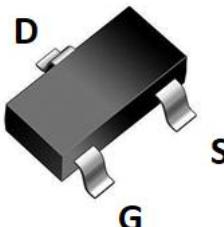
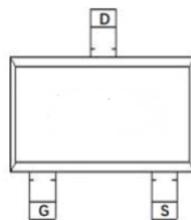
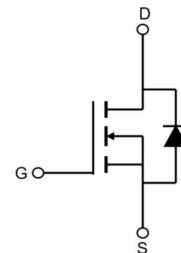
**SDM021NU02S**
**20V N-Channel MOSFETs**
**Rev 1.0**
**Feature**

- ✧ Excellent  $R_{DS(ON)}$
- ✧ Low Gate Charge
- ✧ High current Capability
- ✧ Green product RoHS compliant

**Product Summary**

$V_{DS}$	20	V
$V_{GS(th)}_{Typ}$	0.7	V
$R_{DS(ON)}_{Typ}$ (@ $V_{GS} = 4.5V$ )	15	$m\Omega$
$I_D$ (at $V_{GS} = 4.5V$ ) <sup>(1)</sup>	6.5	A

Type	Package	Marking	Outline	Media	Quantity (pcs)
SDM021NU02S	SOT-23	021N02	Tape	7" Reel	3000


**SOT-23 top view**

**Pin Assignment**

**Schematic Diagram**
**Absolute Maximum Ratings (Rating at  $T_J=25^\circ C$  unless otherwise noted)**

Parameter	Symbol	Maximum	Unit
Drain-Source Voltage	$V_{DS}$	20	V
Gate-Source Voltage	$V_{GS}$	$\pm 12$	V
Continuous Drain Current <sup>(1)</sup>	$I_D$	6.5	A
		4.1	
Pulsed Drain Current <sup>(2)</sup>	$I_{DM}$	26	A
Maximum Body-Diode Continuous Current	$I_S$	6.5	A
Avalanche Current <sup>(3)</sup>	$I_{AS}$	13	A
Avalanche Energy <sup>(3)</sup>	$E_{AS}$	17	mJ
Power Dissipation <sup>(4)</sup>	$P_D$	1.3	W
		0.5	
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to +150	°C

# SDM021NU02S

**Electrical Characteristics** (Rating at  $T_J=25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>STATIC PARAMETERS</b>						
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$I_D=250\mu\text{A}, V_{GS}=0\text{V}$	20	-	-	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{DS}=20\text{V}, V_{GS}=0\text{V}$ $T_J=55^\circ\text{C}$	-	-	1	$\mu\text{A}$
			-	-	5	
$I_{\text{GSS}}$	Gate-Body Leakage Current	$V_{DS}=0\text{V}, V_{GS}=\pm 12\text{V}$	-	-	$\pm 100$	nA
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	0.5	0.7	1	V
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{GS}=4.5\text{V}, I_D=4\text{A}$	-	15	21	$\text{m}\Omega$
		$V_{GS}=2.5\text{V}, I_D=3\text{A}$	-	18	30	
$g_{\text{FS}}$	Forward Transconductance	$V_{DS}=5\text{V}, I_D=4\text{A}$	-	10	-	S
$V_{\text{SD}}$	Diode Forward Voltage	$I_S=3\text{A}, V_{GS}=0\text{V}$	-	0.8	1	V
<b>DYNAMIC PARAMETERS</b> <sup>(5)</sup>						
$C_{\text{iss}}$	Input Capacitance	$V_{GS}=0\text{V}, V_{DS}=10\text{V}, f=1\text{MHz}$	-	30	-	pF
$C_{\text{oss}}$	Output Capacitance		-	10	-	pF
$C_{\text{rss}}$	Reverse Transfer Capacitance		-	13	-	pF
$R_g$	Gate Resistance	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1\text{MHz}$	-	40	-	$\Omega$
<b>SWITCHING PARAMETERS</b> <sup>(5)</sup>						
$Q_g$	Total Gate Charge	$V_{GS}=4.5\text{V}, V_{DS}=10\text{V}, I_D=3\text{A}$	-	9.5	-	nC
$Q_{\text{gs}}$	Gate Source Charge		-	1.7	-	nC
$Q_{\text{gd}}$	Gate Drain Charge		-	2.1	-	nC
$t_{\text{D(on)}}$	Turn-On Delay Time	$V_{GS}=4.5\text{V}, V_{DS}=10\text{V}, I_D=3\text{A}, R_{\text{GEN}}=3\Omega$	-	3.9	-	ns
$t_r$	Turn-On Rise Time		-	17	-	ns
$t_{\text{D(off)}}$	Turn-Off Delay Time		-	105	-	ns
$t_f$	Turn-Off Fall Time		-	63	-	ns
$t_{\text{rr}}$	Body Diode Reverse Recovery Time	$I_F=3\text{A}, di/dt=100\text{A}/\mu\text{s}$	-	29	-	ns
$Q_{\text{rr}}$	Body Diode Reverse Recovery Charge	$I_F=3\text{A}, di/dt=100\text{A}/\mu\text{s}$	-	7.1	-	nC

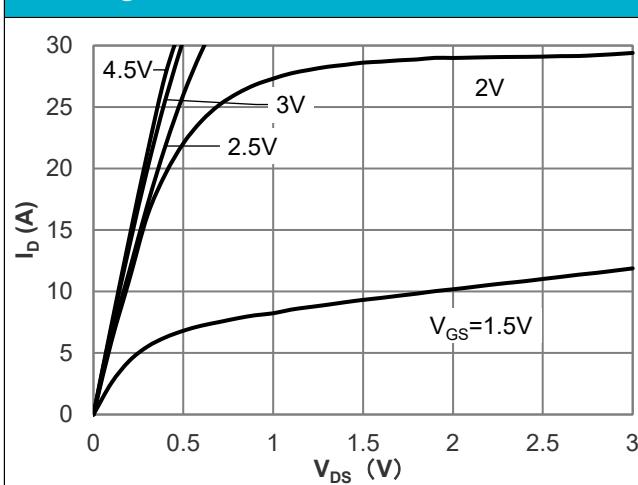
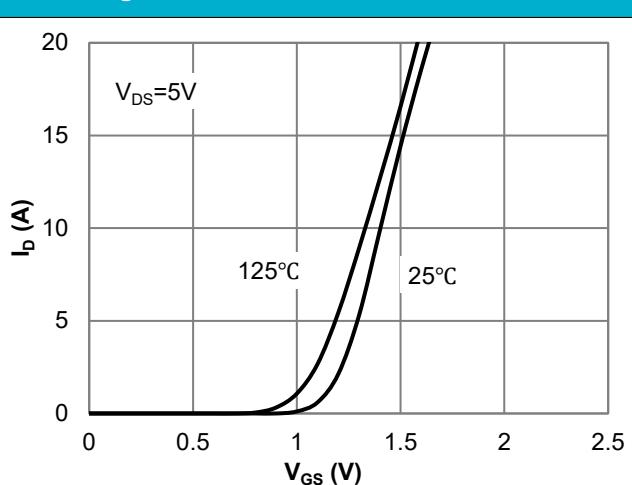
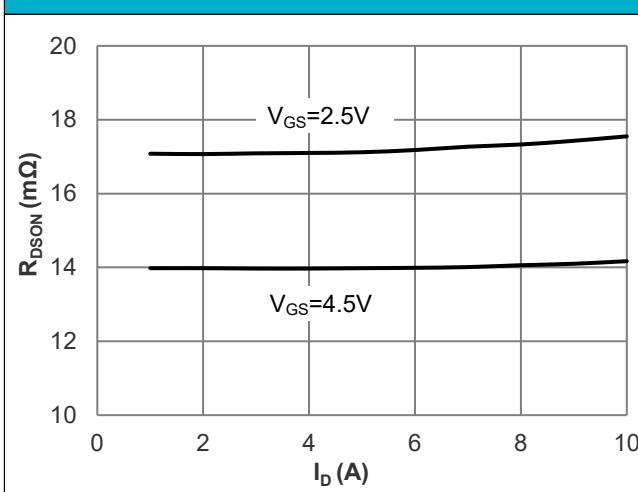
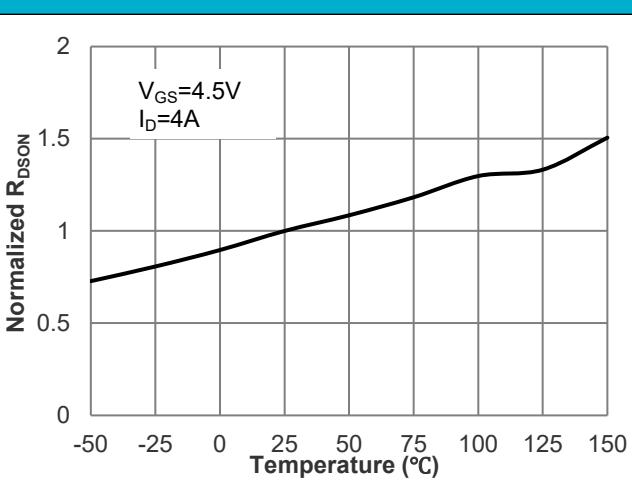
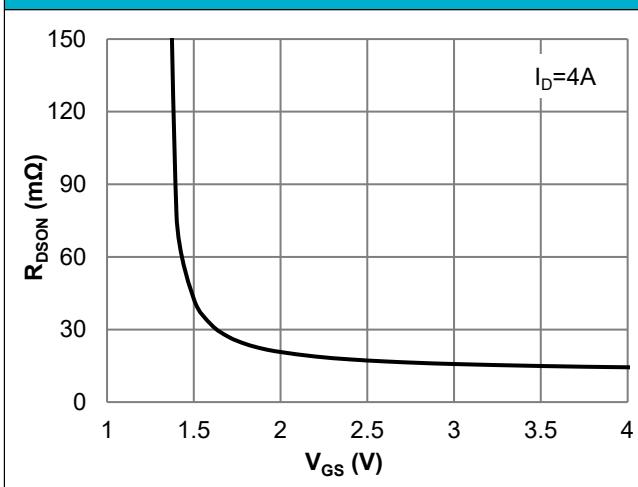
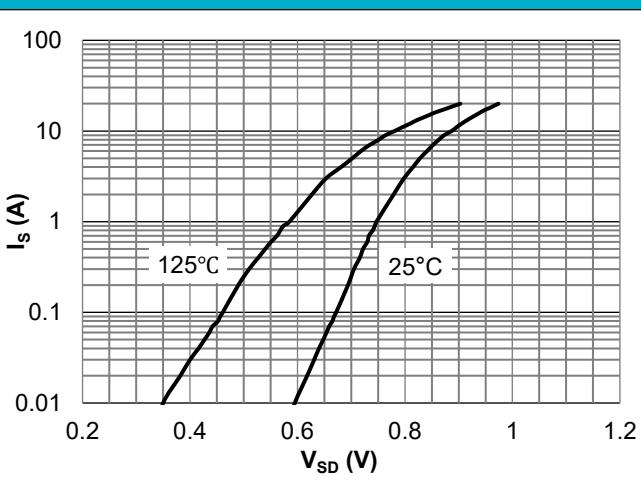
## Thermal Resistances

Symbol	Parameter	Typ	Max	Unit
$R_{\theta\text{JC}}$	Thermal resistance from junction to case	-	-	$^\circ\text{C}/\text{W}$
$R_{\theta\text{JA}}$	Thermal resistance from junction to ambient	-	94	$^\circ\text{C}/\text{W}$

## Notes:

1. Computed continuous current assumes the condition of  $T_{J,\text{Max}}$  while the actual continuous depends on the thermal & electro-mechanical application board design.
2. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
3. This single-pulse measurement was taken under the following condition [ $L=0.1\text{mH}, V_{GS}=10\text{V}, V_{DS}=10\text{V}$ ] while its value is limited by  $T_{J,\text{Max}}=150^\circ\text{C}$ .
4. The power dissipation  $P_D$  is based on  $T_{J,\text{Max}}=150^\circ\text{C}$ .
5. This value is guaranteed by design hence it is not included in the production test.

## Typical Electrical and Thermal Characteristics

**Figure 1: Saturation Characteristics****Figure 2: Transfer Characteristics****Figure 3:  $R_{DS(ON)}$  vs. Drain Current****Figure 4:  $R_{DS(ON)}$  vs. Junction Temperature****Figure 5:  $R_{DS(ON)}$  vs. Gate-Source Voltage****Figure 6: Body-Diode Characteristics**

## Typical Electrical and Thermal Characteristics

Figure 7: Gate-Charge characteristics

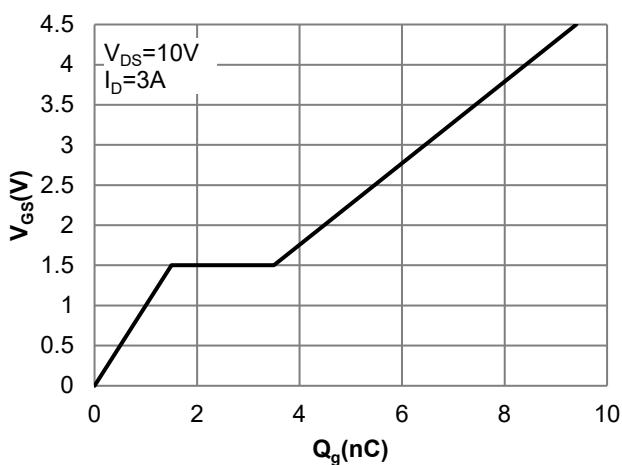


Figure 8: Capacitance characteristics

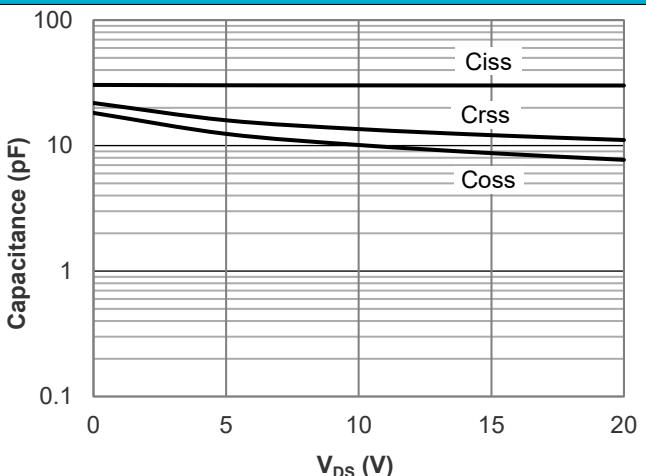


Figure 9: Current De-rating

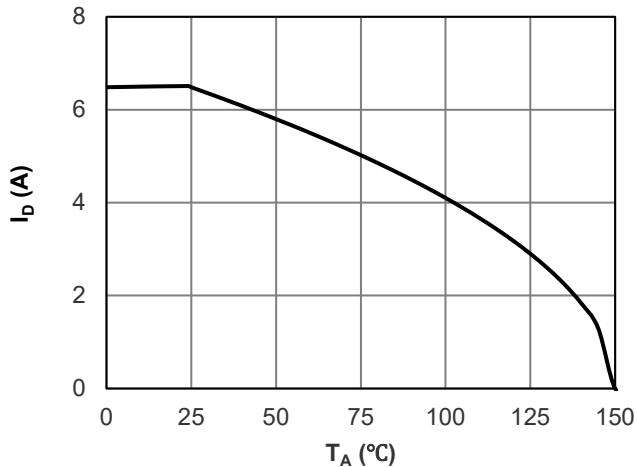


Figure 10: Power De-rating

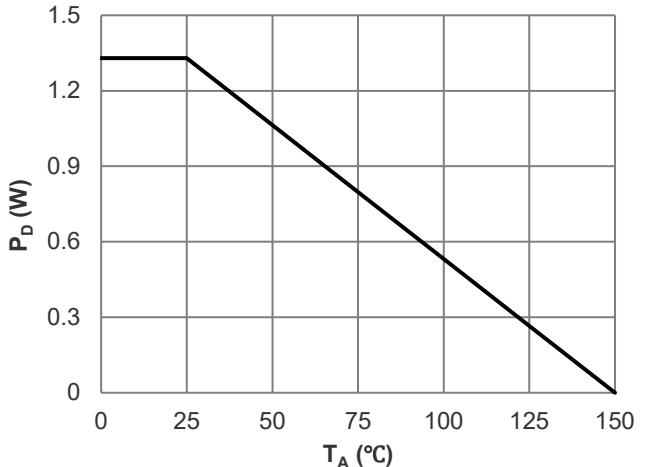


Figure 11: Maximum Safe Operating Area

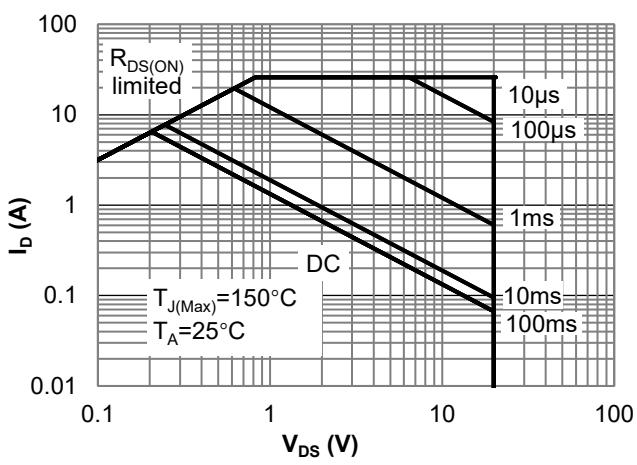
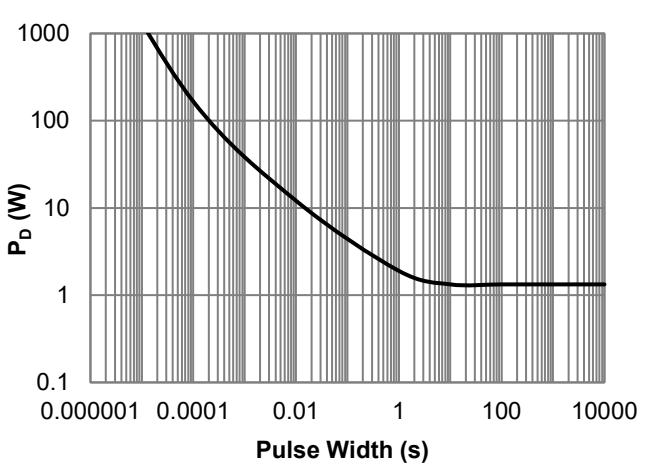
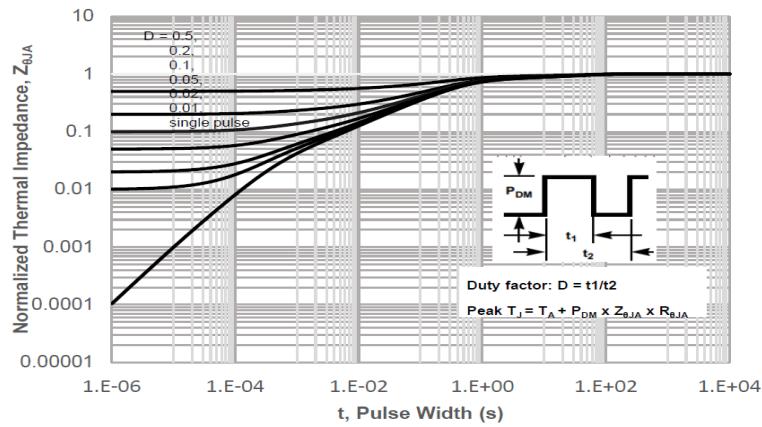


Figure 12: Peak Current Capacity



## Typical Electrical and Thermal Characteristics

Figure 13: Normalized Maximum Transient Thermal Impedance



## Test Circuit

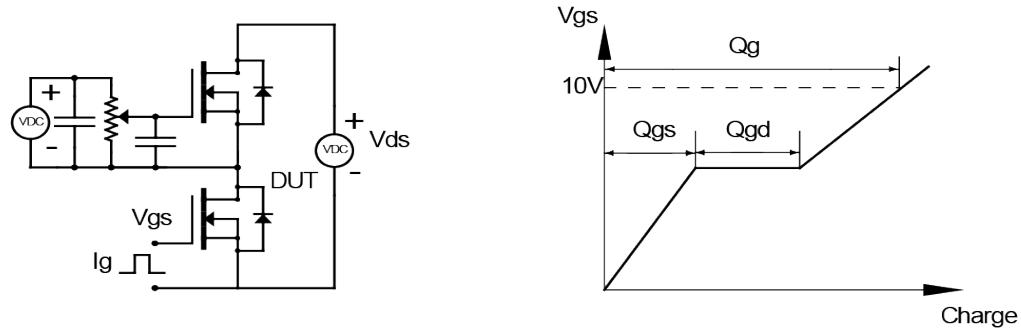


Figure1: Gate Charge Test Circuit &amp; Waveforms

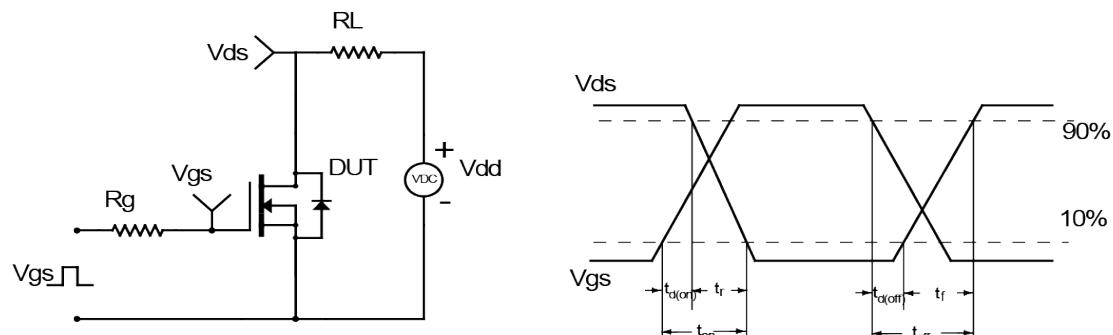


Figure2: Resistive Switching Test Circuit &amp; Waveforms

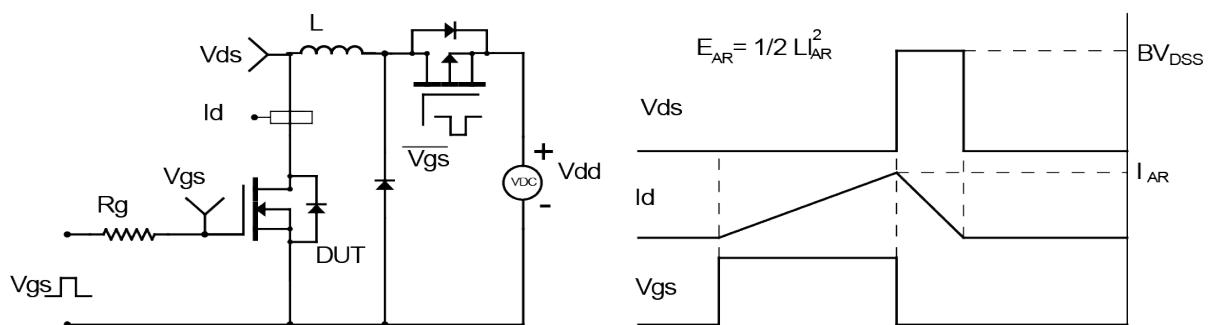


Figure3: Unclamped Inductive Switching (UIS) Test Circuit &amp; Waveforms

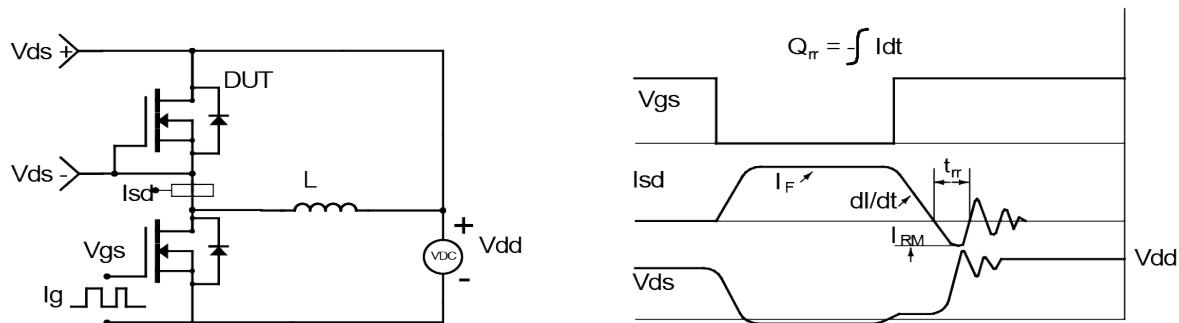
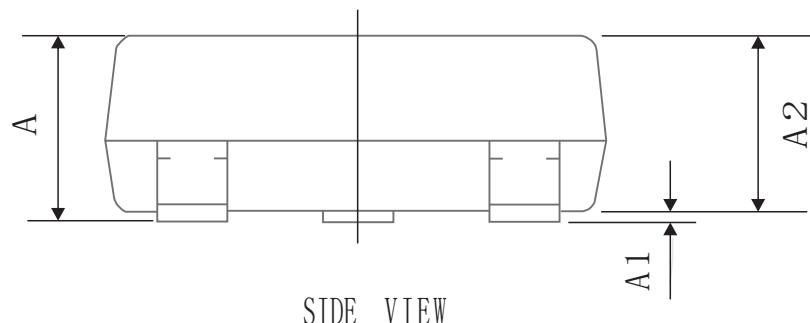
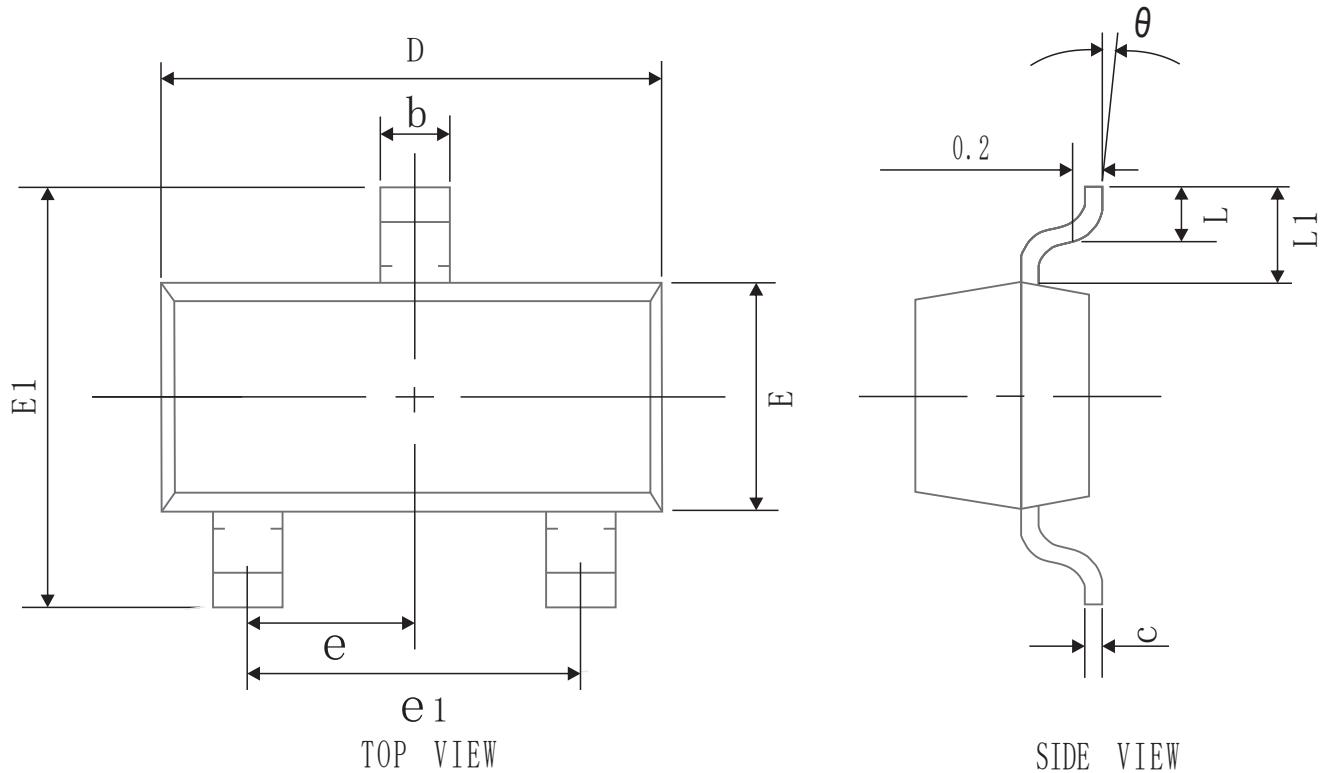


Figure4: Diode Recovery Test Circuit &amp; Waveforms

## SOT-23 Package Information



SYMBOL	MIN	NOM	MAX
A	0.90	.05	.20
A1	0.00	.05	.10
A2	0.90	.00	.10
b	0.30	.40	.50
c	0.08	.10	.15
D	2.80	.90	.00
E	1.20	.30	.40
E1	2.30	.40	.50
L	0.30	.40	.50
θ	0°	5°	0°
L1	0.55 REF		
e	0.95 BSC		
e1	1.90 REF		